

Abstract of the Disclosure

A method and apparatus electrically coupling input/output bond pads that are disposed proximate to one another on a microelectronic device. The apparatus includes a microelectronic device having at least two conductive input/output bond pads electrically coupled to an integrated circuit of the microelectronic device and first and second conductive stud balls bonded to first and second input/output pads, respectively, and a third conductive stud ball bonded to the first and second conductive stud balls. A wire bonding tool in "stud ball" mode is utilized to bond the conductive stud balls.